

Product Description

Shin-Etsu's KE-1855 is a single component, heat cure, thixotropic adhesive that will cure to form a tough, durable elastomer. KE-1855 exhibits excellent, unprimed adhesion to metals, plastics, glass, and ceramics.

Product Features

- High strength
- Single component
- Heat cured
- High viscosity paste

Typical Applications

- Form-in-place gasketing
- Sealing electronics

Typical Properties

Type	Adhesive/Sealant
Cure Type	Addition
One/Two Component	One
Cold Storage	Y
Color	Gray
Density @ 23C (g/cm ³)	1.28
Viscosity (Pa·s)	60.00
Cure Conditions	1hr @ 120C
Shore A Hardness	66
Tensile Strength (MPa)	6.70
% Elongation	150
Shear Strength (MPa)	3.50
Volume Resistivity (TΩ·m)	5.0
Dielectric Strength (kV/mm)	25
Dielectric Constant	3.5 @ 50Hz
Dielectric Dissipation Factor	5x10 ⁻³ @ 50Hz
Thermal Conductivity (W/m·K)	0.27
Usable Temperature Range (C)	-40 to +180

Note: Values are not for specification purposes.

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